

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended): An apparatus for removing metal from a metallized surface of a workpiece, comprising:

a polishing pad,

an electrically conductive surface having more than one zone disposed proximate to said polishing pad wherein the zones are separated by one or more insulators;

at least one conducting element disposed within each zone of the electrically conductive surface;

a workpiece carrier configured to press the workpiece against the polishing pad; and

a plurality of power sources each having a first positive output connected to the conducting element and a second negative output connected to the electrically conductive surface contained within each of the zones of the conductive surface.

2. (Original): The apparatus of claim 1 wherein said at least one conducting element is positioned flush with a top surface of said polishing pad.

3. (Original): The apparatus of claim 1 wherein said at least one conducting element is positioned above a top surface of said polishing pad.

4. (Original): The apparatus of claim 1 wherein said at least one conducting element is positioned below a top surface of said polishing pad.

5. (Currently Amended): The apparatus of claim 1 wherein said conducting elements are positioned within the electrically conductive surface such that a uniform electric potential gradient is created across each zone of the metallized surface of the wafer.

6. (Original): The apparatus of claim 1 wherein said at least one conducting element is comprised of a material that exhibits low electrical resistance and resistance to corrosion.

7. (Original): The apparatus of claim 1 wherein the distance between the metallized surface of the workpiece and the electrically conductive surface is less than 3 mm.

8. (Original): The apparatus of claim 7 wherein the distance between the metallized surface of the workpiece and the electrically conductive surface is less than 1 mm.

9. (Original): The apparatus of claim 8 wherein the distance between the metallized surface of the workpiece and the electrically conductive surface is less than 200 angstroms.

10. (Original): The apparatus of claim 1 wherein the metallized surface of the workpiece does not contact the electrically conductive surface during removal of the metal from the metallized surface of the workpiece.

11. (New): An apparatus for removing metal from a metallized surface of a workpiece, comprising:

a polishing pad;

an electrically conductive platen disposed proximate to said polishing pad comprising a top cover plate, a bottom section plate, and an intermediate channel plate having channel grooves positioned between the top and bottom plates;

at least one conducting element disposed within the electrically conductive platen;

a workpiece carrier configured to press the workpiece against the polishing pad;

and

a power source having a first positive output connected to the conducting element and a second negative output connected to the electrically conductive platen.

12. (New): The apparatus of claim 11 wherein said at least one conducting element is positioned flush with a top surface of said polishing pad.

13. (New): The apparatus of claim 11 wherein said at least one conducting element is positioned above a top surface of said polishing pad.

14. (New): The apparatus of claim 11 wherein said at least one conducting element is positioned below a top surface of said polishing pad.

15. (New): The apparatus of claim 11 wherein said conducting elements are positioned within the electrically conductive platen such that a uniform electric potential gradient is created across the metallized platen of the wafer.

16. (New): The apparatus of claim 11 wherein said at least one conducting element is comprised of a material that exhibits low electrical resistance and resistance to corrosion.

17. (New): The apparatus of claim 11 wherein the distance between the metallized platen of the workpiece and the electrically conductive platen is less than 3 mm.

18. (New): The apparatus of claim 17 wherein the distance between the metallized platen of the workpiece and the electrically conductive platen is less than 1 mm.

19. (New): The apparatus of claim 18 wherein the distance between the metallized platen of the workpiece and the electrically conductive platen is less than 200 angstroms.

20. (New): The apparatus of claim 11 wherein the metallized platen of the workpiece does not contact the electrically conductive platen during removal of the metal from the metallized platen of the workpiece.